



04-24-2009

PATENT

IN THE UNITEDMARK OFFICEREQ

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Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Please record the attached assignment document.

1. Name of conveying parties: Mitsuo ZEN  
Hirokazu ICHIKAWA  
Satoshi OZAWA
2. Name and address of receiving party: Senju Metal Industry Co., Ltd.  
23 Senju-Hashido-cho,  
Adachi-ku,  
Tokyo 120-8555, Japan
3. Nature of conveyance: Assignment  
Execution dates of assignment:  
March 11, 2009 for ZEN  
February 26, 2009 for ICHIKAWA  
March 3, 2009 for OZAWA
4. U.S. Application No.: 12/226,654  
International filing date: April 24, 2007

04/23/2009 MJAMA1 00000007 12226654  
01 FC:0021

40.00 OP

5. Name and address of party to whom correspondence concerning the attached document should be mailed:

Michael Tobias  
1629 K Street N.W., Suite 300  
Washington, D.C. 20006  
Tel: (301) 571-0052

6. Total number of applications involved: 1

7. Total fee: \$40.00  
[X] Enclosed  
[ ] Authorized to be charged to the deposit account  
[X] The Commissioner is authorized to charge any deficiencies in the fee payment accompanying this communication and to credit any excess payment of fees to Deposit Account No. 50-1079.

8. Statement and signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

April 2, 2009  
Date

Michael Tobias  
Michael Tobias  
Registration No. 32,948  
Customer No. 27649

Total number of pages comprising cover sheet, attachments and document: 4

## ASSIGNMENT

WHEREAS, We, **Mitsuo ZEN, Hirokazu ICHIKAWA and Satoshi OZAWA**, residing in Souka-shi, Saitama; Souka-shi, Saitama; and Chiba-shi, Chiba, all Japan, respectively, have invented certain new and useful improvements entitled

### WAVE SOLDERING TANK

(a) for which an application for United States Letters Patent was filed on

October 24, 2008

and identified by United States Serial No. 12/226,654; or

(b) for which an application for United States Letters Patent was executed on

AND, WHEREAS, **SENJU METAL INDUSTRY CO., LTD.**, a corporation of Japan, having a place of business at **23 Senju-Hashido-cho, Adachi-ku, Tokyo 120-8555, Japan**, hereinafter called the "assignee", is desirous of acquiring the entire right, title, and interest in and to said application and the inventions and improvements therein disclosed.

NOW, THEREFORE, for good and valuable consideration paid to us by said assignee, the receipt of which is hereby acknowledged, we do hereby assign, sell, transfer, and set over unto said assignee the entire right, title and interest in and to said application and the inventions and improvements therein disclosed for the United States and all foreign countries and any Letters Patent which may issue therefor in the United States and all foreign countries and all divisions, reissues, continuations, continuations-in-part, renewals, and/or extensions thereof, said assignee to have and to hold the interests herein assigned to the full ends of the terms of said Letters Patent and any and all divisions, reissues, continuations, continuations-in-part, renewals, and/or extensions thereof, respectively, as fully and entirely as the same would have been held and enjoyed by us had this assignment not been made.

The Commissioner for Patents is requested to issue such Letters Patent in accordance herewith. We covenant that we are the lawful owners of the said application, inventions, and improvements, that the same are unencumbered, that no license has been granted to make, use, or vend the said inventions or improvements or any of them, and that we have the full right to make this assignment.

And for the consideration aforesaid, we agree jointly and individually that we will communicate to said assignee or the representatives thereof any facts known to us respecting said inventions and improvements, and will, upon request, but without expense to us, testify in any legal proceedings, sign all lawful papers, execute all divisional, reissue, continuation, continuations-in-part, renewal, and/or extension applications, make all rightful oaths, and generally do all other and further lawful acts,

deemed necessary or expedient by said assignee or by counsel for said assignee, to assist or enable said assignee to obtain and enforce full benefits from the rights and interests herein assigned. This assignment shall be binding upon our heirs, executors, administrators, and/or assigns, and shall inure to the benefit of the heirs, executors, administrators, successors, and/or assigns, as the case may be, of said assignee.

We authorize the assignee and its agents to insert or to have inserted in this instrument the execution date/or the filing date and serial number of our patent application.

Dated: March 11. 2009

Mitsuo Zen  
Mitsuo ZEN

Dated: February 26. 2009

Hirokazu Ichikawa  
Hirokazu ICHIKAWA

Dated: March 3. 2009

Satoshi Ozawa  
Satoshi OZAWA